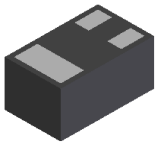
Features

- BV_{CEO} > -50V
- I_C = -100mA High Collector Current
- P_D = 1000mW Power Dissipation
- 0.60mm^2 Package Footprint, 13 times Smaller than SOT23
- 0.4mm Height Package Minimizing Off-Board Profile
- Complementary NPN Type: DN0150ALP4 / DN0150BLP4
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

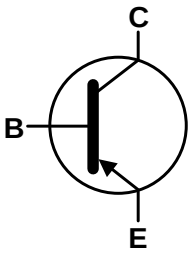
Mechanical Data

- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu.
- Solderable per MIL-STD-202, Method 208 e4
- Weight: 0.0008 grams (Approximate)

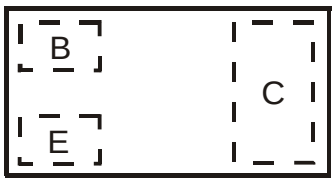
X2-DFN1006-3



Bottom View



Device Symbol



Top View
Pin Configuration

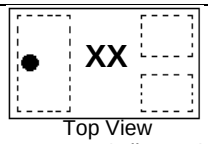
Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DP0150ALP4-7	T5	7	8	3,000
DP0150ALP4-7B	T5	7	8	10,000
DP0150BLP4-7	T6	7	8	3,000
DP0150BLP4-7B	T6	7	8	10,000

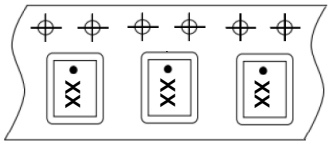
Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

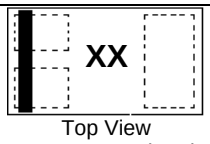
DP0150ALP4-7
DP0150BLP4-7



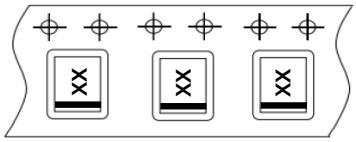
Top View
Dot Denotes Collector Side



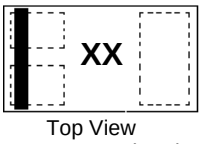
From date code 1527 (YYWW), this changes to:



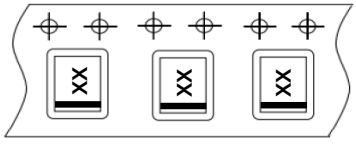
Top View
Bar Denotes Base and Emitter Side



DP0150ALP4-7B
DP0150BLP4-7B



Top View
Bar Denotes Base and Emitter Side



XX = Product Type Marking Code
(See Ordering Information)

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-50	V
Collector-Emitter Voltage	V_{CEO}	-50	V
Emitter-Base Voltage	V_{EBO}	-5	V
Collector Current - Continuous	I_C	-100	mA
Peak Pulse Collector Current	I_{CM}	-200	mA
Base Current	I_B	-30	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 5)	P_D	400	mW
	(Note 6)		1000	
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{\theta JA}$	310	°C/W
	(Note 6)		120	
Thermal Resistance, Junction to Lead	(Note 7)	$R_{\theta JL}$	120	°C/W
Operating and Storage and Temperature Range		T_J, T_{STG}	-55 to +150	°C

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS							
Collector-Base Breakdown Voltage		BV_{CBO}	-50	—	—	V	I_C = -10μA, I_E = 0
Collector-Emitter Breakdown Voltage (Note 8)		BV_{CEO}	-50	—	—	V	I_C = -1mA, I_B = 0
Emitter-Base Breakdown Voltage		BV_{EBO}	-5	—	—	V	I_E = -10μA, I_C = 0
Collector Cut-Off Current		I_{CBO}	—	—	-0.1	μA	V_{CB} = -50V, I_E = 0
Emitter Cut-Off Current		I_{EBO}	—	—	-0.1	μA	V_{EB} = -5V, I_C = 0
ON CHARACTERISTICS (Note 9)							
Collector-Emitter Saturation Voltage		$V_{CE(SAT)}$	—	-0.15	-0.3	V	I_C = -100mA, I_B = -10mA
DC Current Gain	DP01510ALP4	h_{FE}	120	—	240	—	V_{CE} = -6V, I_C = -2mA
	DP01510BLP4		200	—	400		
SMALL SIGNAL CHARACTERISTICS							
Transition Frequency		f_T	80	—	—	MHz	V_{CE} = -10V, I_E = 1mA f = 30MHz
Output Capacitance		C_{ob}	—	1.6	—	pF	V_{CB} = -10V, I_E = 0, f = 1MHz

Notes:
5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
6. Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.
7. Thermal resistance from junction to solder-point (on the exposed collector pad).
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.
9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

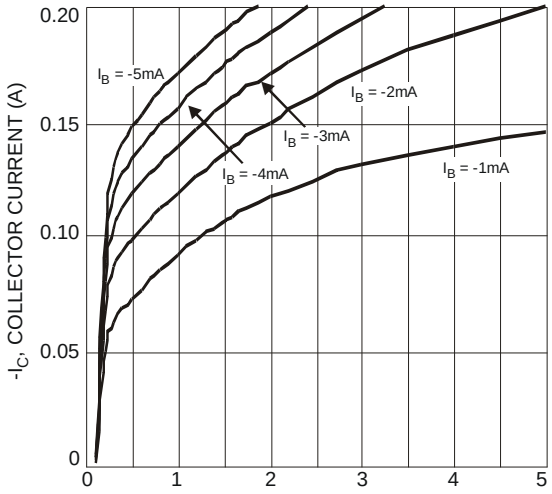


Fig. 2 Typical Collector Current
vs. Collector-Emitter Voltage (DN0150BLP4)

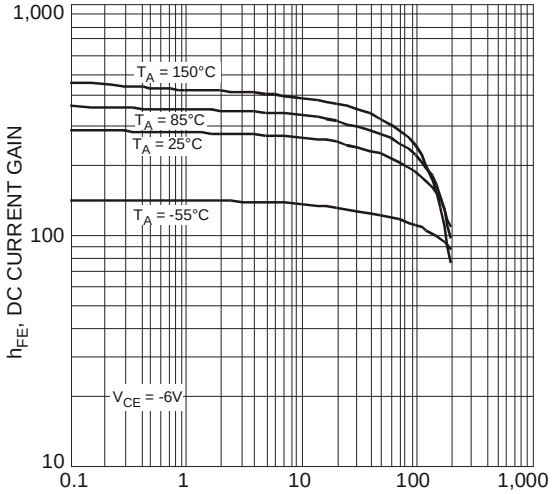


Fig. 3 Typical DC Current Gain
vs. Collector Current (DN0150BLP4)

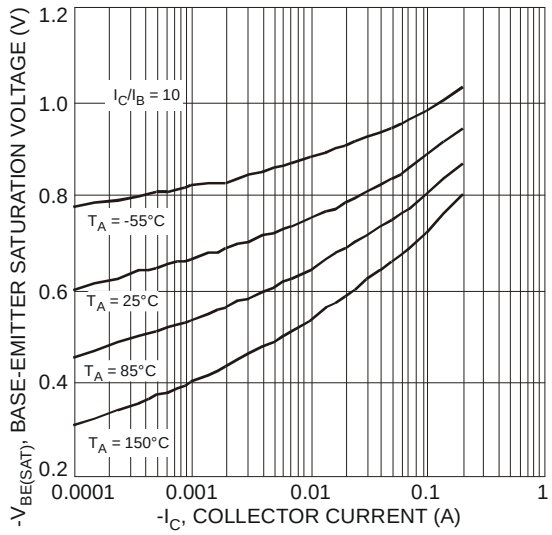


Fig. 6 Typical Base-Emitter Saturation Voltage
vs. Collector Current

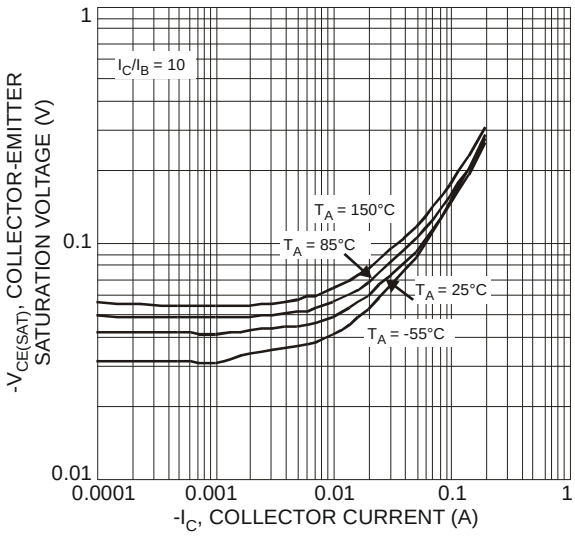


Fig. 4 Typical Collector-Emitter Saturation Voltage
vs. Collector Current

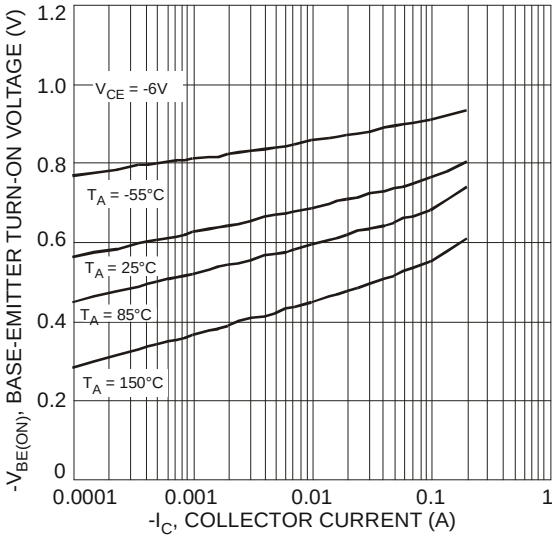


Fig. 5 Typical Base-Emitter Turn-On Voltage
vs. Collector Current

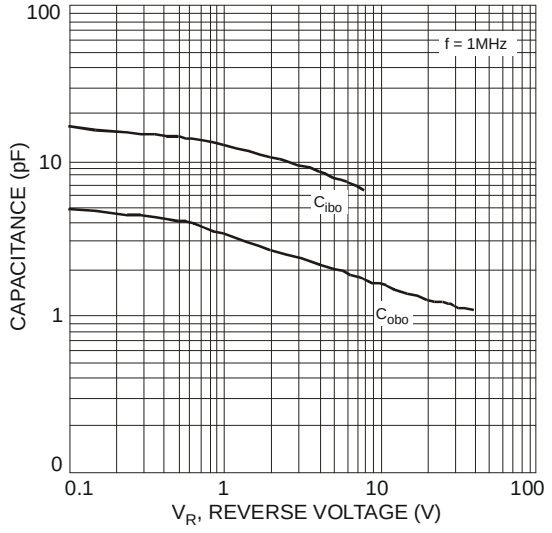


Fig. 7 Typical Capacitance Characteristics

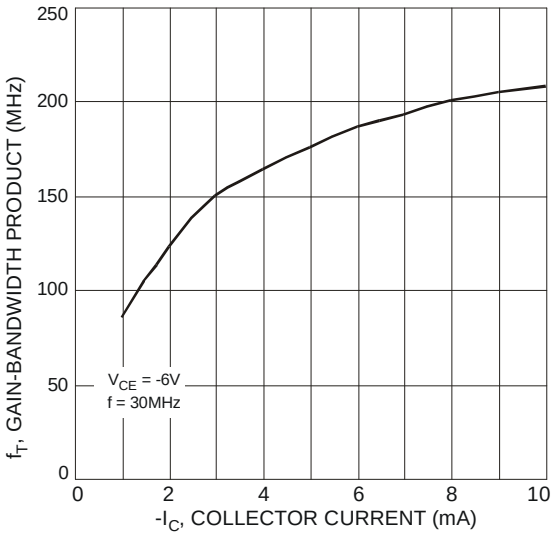
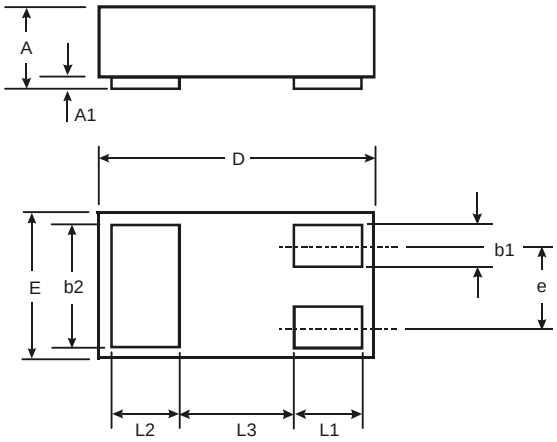


Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

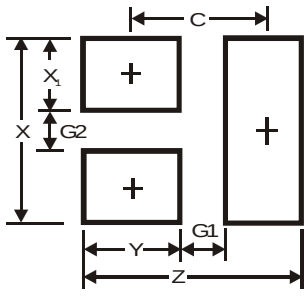
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X2-DFN1006-3			
Dim	**Min**	**Max**	**Typ**
A	—	0.40	—
A1	0	0.05	0.02
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.05	1.00
E	0.55	0.65	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

www.diodes.com